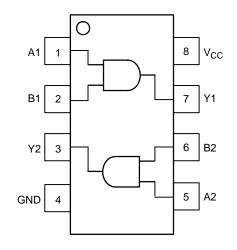
## **Dual 2-Input AND Gate**

The NL27WZ08 is a high performance dual 2-input AND Gate operating from a 1.65 V to 5.5 V supply.

- Extremely High Speed:  $t_{PD}$  2.5 ns (typical) at  $V_{CC} = 5 V$
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with  $V_{CC}$  = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7WZ08
- Chip Complexity: FET = 124



### Figure 1. Pinout

### PIN ASSIGNMENT

Pin	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V <sub>CC</sub>

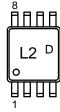


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MARKING DIAGRAM

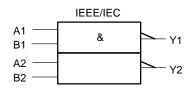




D = Date Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.





## FUNCTION TABLE

ľ	=	AB	

Inp	Output	
Α	В	Y
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

H = HIGH Logic Level

L = LOW Logic Level

### **MAXIMUM RATINGS**

Symbol	Pa	rameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		-0.5 to +7.0	V
Vo	DC Output Voltage		-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>1</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
I <sub>O</sub>	DC Output Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance	(Note 1)	250	°C/W
PD	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>Latch-Up</sub>	Latch–Up Performance	Above $V_{CC}$ and Below GND at 85°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

Tested to EIA/JESD22–A114–A.
 Tested to EIA/JESD22–A115–A.

4. Tested to JESD22-C101-A.

5. Tested to EIA/JESD78.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	(Note 6)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free–Air Temperature		-40	+ 85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 V \pm 0.2 V V_{CC} = 3.0 V \pm 0.3 V V_{CC} = 5.0 V \pm 0.5 V$	0 0 0	20 10 5	ns/V

6. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

### DC ELECTRICAL CHARACTERISTICS

			Vcc	Т	<sub>A</sub> = 25°0	2	-40°C ≤ .		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High–Level Input Voltage		1.65 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High–Level Output Voltage $V_{IN} = V_{IL}$ or $V_{IH}$	$\begin{split} I_{OH} &= 100 \ \mu A \\ I_{OH} &= -3 \ m A \\ I_{OH} &= -8 \ m A \\ I_{OH} &= -12 \ m A \\ I_{OH} &= -16 \ m A \\ I_{OH} &= -24 \ m A \\ I_{OH} &= -32 \ m A \end{split}$	1.65 to 5.5 165 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.5 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.5 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low–Level Output Voltage $V_{IN} = V_{IH}$ or $V_{OH}$	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ mA$ $I_{OL} = 8 \ mA$ $I_{OL} = 12 \ mA$ $I_{OL} = 16 \ mA$ $I_{OL} = 24 \ mA$ $I_{OL} = 32 \ mA$	1.65 to 5.5 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			±0.1		±1.0	μA
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC} \text{ or } GND$	5.5			1.0		10	μA

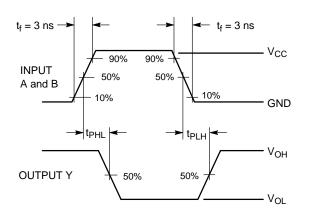
### AC ELECTRICAL CHARACTERISTICS $t_{R}$ = $t_{F}$ = 3.0 ns

			V <sub>CC</sub>	•	T <sub>A</sub> = 25°C	;	-40°C ≤ -	Γ <sub>A</sub> ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	$1.8~\pm~0.15$	2.0	5.7	10.5	2.0	11.0	ns
t <sub>PHL</sub>	(Figure 3 and 4)		$2.5\pm0.2$	1.0	3.5	5.8	2.0	6.2	
		$ \begin{array}{l} R_{L} = 1 \; M\Omega,  C_{L} = 15 \; pF \\ R_{L} = 500 \; \Omega,  C_{L} = 50 \; pF \end{array} $	3.3 ± 0.3	0.8 1.2	2.6 3.2	3.9 4.8	0.8 1.2	4.3 5.2	
		$ \begin{array}{l} R_{L} = 1 \; M\Omega,  C_{L} = 15 \; pF \\ R_{L} = 500 \; \Omega,  C_{L} = 50 \; pF \end{array} $	5.0 ± 0.5	0.5 0.8	1.9 2.5	3.1 3.7	0.5 0.8	3.3 4.0	

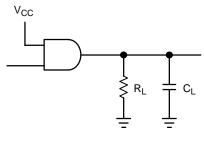
### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_{I}$ = 0 V or $V_{CC}$	4	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 7)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25 30	pF

7.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .







A 1–MHz square input wave is recommended for propagation delay tests.



### **DEVICE ORDERING INFORMATION**

	Device Nomenclature							
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Package Type	Tape and Reel Size
NL27WZ08US	NL	2	7	WZ	08	US	US8	178 mm, 3000 Unit

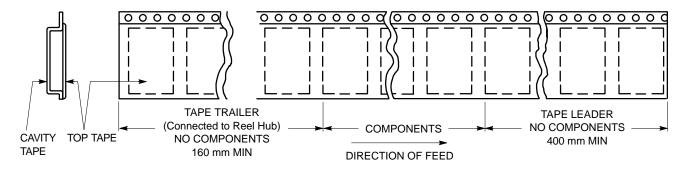


Figure 5. Tape Ends for Finished Goods

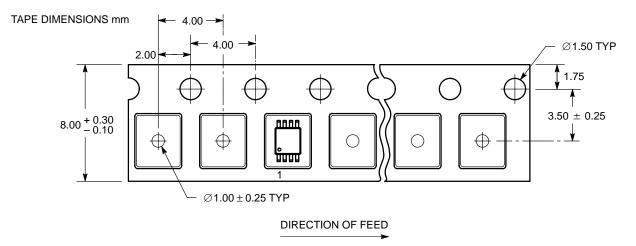
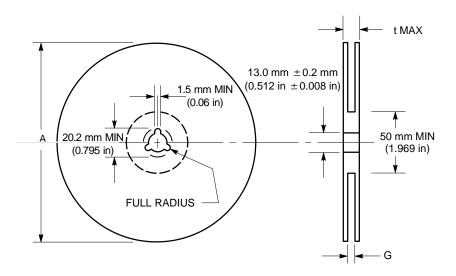


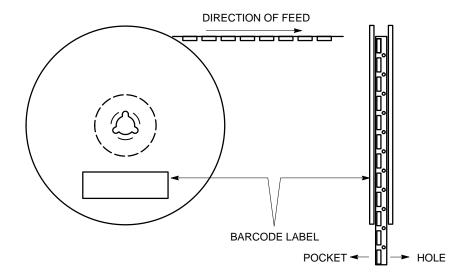
Figure 6. US8 Reel Configuration/Orientation





### **REEL DIMENSIONS**

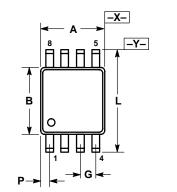
Tape Size	T and R Suffix	A Max	G	t Max
8 mm	US	178 mm (7 in)	8.4 mm, + 1.5 mm, –0.0 (0.33 in + 0.059 in, –0.00)	14.4 mm (0.56 in)





### PACKAGE DIMENSIONS

US8 **US SUFFIX** CASE 493-01 ISSUE O



-T-

SEATING PLANE

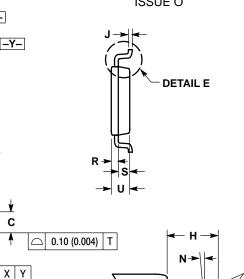
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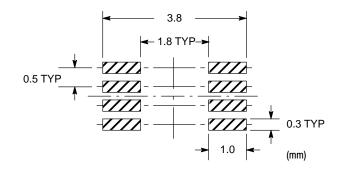
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- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. DIMENSION 'A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION OR GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055') PER SIDE. 4. DIMENSION 'B' DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION. SHALL NOT E3XCEED 0.140 (0.0055') PER SIDE. 5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800 INCH).
- INCH). 6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0002").

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.90	2.10	0.075	0.083
В	2.20	2.40	0.087	0.094
С	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020	) BSC
Η	0.40	REF	0.016 REF	
ſ	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.126
Μ	0 °	6 °	0 °	6 °
Ν	5 °	10 °	5 °	10 °
Ρ	0.28	0.44	0.011	0.017
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
۷	0.12	BSC	0.005	5 BSC



DETAIL E

4

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